

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHEK HONG	10/24/2014
RECEIVING PARTY DATA	
Name:	HONTEK CORPORATION
Street Address:	161 SATELLITE ROAD
City:	SOUTH WINDSOR
State/Country:	CONNECTICUT
Postal Code:	06074
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14052035
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 2:	SUITE 206
Address Line 4:	MIDDLETOWN, CONNECTICUT 06457
ATTORNEY DOCKET NUMBER:	1135-0001-3DIV
NAME OF SUBMITTER:	MICHAEL K. KINNEY
SIGNATURE:	/Michael K. Kinney/
DATE SIGNED:	06/29/2015
Total Attachments: 2	
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ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated below my names, as an inventor of certain new and useful improvements in **ABRASION RESISTANT COATINGS**, for which a non-provisional application was filed in the U.S. Patent and Trademark Office on October 11, 2013 and has been assigned Application No. 14/052,035, which is a divisional application of U.S. Application Serial No. 12/815,963, filed June 15, 2010, now issued as U.S. Patent No. 8,557,388, which is a continuation application of U.S. Application Serial No. 11/136,827, filed May 24, 2005, now issued as U.S. Patent No. 7,736,745, which claims the benefit of U.S. Provisional Application Serial No. 60/573,819 filed May 24, 2004 and U.S. Provisional Application Serial No. 60/649,443 filed February 2, 2005.

WHEREAS, I possess the entire right, title and interest in the foregoing invention, free from all encumbrances, and have full right to convey his part or all of his interest, and

WHEREAS, Hontek Corporation (hereinafter referenced as ASSIGNEE), a Connecticut corporation having a place of business at 161 South Satellite Road, South Windsor, CT 06074, is desirous of acquiring all rights, title and interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole inventor, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the full, exclusive and entire right, title and interest in the said invention, said applications, and any divisions, continuations and reissues thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and the right to sue and collect damages for past infringement, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

AND I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time to time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

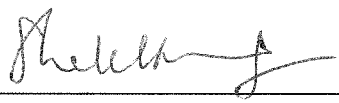
Docket Number: 1135-0001-3DIV

AND I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reexaminations, reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

AND I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any reexamination, interference or litigation related thereto;

AND I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

Witness



Shek Hong
212 Knollwood Drive
Glastonbury, CT 06033

10/24/2014
Date

Witness